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5 Channel model implementation for evaluation of location services

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Pages:226 - 235

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Pages:751 - 760

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Hairong Sun; Han, J.J.; Levendel, H.;
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 Electron Devices, IEEE Transactions on , Volume: 39 , Issue: 7 , July 1992
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 ... Output/Input Capacitance **ratio** of each stage ... Short **circuit** - may change as shorted output changes. ... will detect all possible stuck-at **faults** (100% **fault coverage**). ...

foghorn.cadlab.lafayette.edu/ece425/notes/12_425_S04.ppt - [Similar pages](#)

ASIC Guide Glossary

 ... **fault coverage** The **ratio** of the count of all detectable **faults** in a **circuit** to the count of those **faults** detected by a particular test set (set of test ...

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Section Three: Chapter Two

 ... A measure called "**fault coverage**" determines a **fault** test set quality ... This measure comes from the **ratio** of the number of **circuit** nodes controlled and ...

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 ... when $x \neq y$ depends on the **ratio** of pull ... adequate BF **coverage** and therefore BF **coverage** estimation is ... The detection of bridging **faults** (equivalent to stuck-on ...

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 ... B. However, set A has to target on transition **faults**. ... set that can provide a complete topological (site) **coverage**. ... D_j where ϵ denotes the **ratio** of partition ...

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 ... of financial information, An introduction to **Ratio** Analysis and ... on quality, The effect of **fault coverage** on quality. ... D3_1, el, Clocking **circuits** and **timing**, Clocking ...

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 ... logic Performance (**timing**) Occurrence frequency (%) 51 1 6 13 6 8 5 5 5 Ref.: J.

 Bateson, In-Circuit Testing, Van Nostrand Reinhold, 1985. Page 11. **Fault** Model ...

www.ece.concordia.ca/~kasiar/fmod.pdf - [Similar pages](#)

Logic Design for Array-Based Circuits - DE White - eBook

 ... Recommended **coverage** is 90% or higher ... simulator systems, but modeling differences make comparisons of **fault** grade scores ... that have a non-one to one **ratio** to pads ...

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Medical Electronics Test - August 1995 - Cardiac Pacemakers

 ... to turn transistors off since these **faults** result in ... but limited by the signal-to-noise **ratio** of the ... it decreases test times without sacrificing test **coverage**. ...

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-	66	(simulat\$3 near3 coverage) and test near3 pattern\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/19 08:20
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